IGBT with Monolithic Free Wheeling Diode

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Field Stop (FS) Trench construction, provides and superior performance in demanding switching applications, and offers low on–state voltage with minimal switching loss. The IGBT is well suited for resonant or soft switching applications.

Features

- Extremely Efficient Trench with Fieldstop Technology
- Low Switching Loss Reduces System Power Dissipation
- Optimized for Low Losses in IH Cooker Application
- Reliable and Cost Effective Single Die Solution
- These are Pb-Free Devices

Typical Applications

- Inductive Heating
- Consumer Appliances
- Soft Switching

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage @ T _J = 25°C	V_{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	Ι _C	40 20	Α
Pulsed collector current, T _{pulse} limited by T _{Jmax} , 10 μs Pulse, V _{GE} = 15 V	I _{CM}	120	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	l _F	40 20	Α
Diode pulsed current, T_{pulse} limited by T_{Jmax} , 10 μs Pulse, V_{GE} = 0 V	I _{FM}	120	Α
Gate-emitter voltage Transient Gate-emitter voltage (T _{pulse} = 5 μs, D < 0.10)	V_{GE}	±20 ±25	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	384 192	W
Operating junction temperature range	TJ	-40 to +175	°C
Storage temperature range	T _{stg}	-55 to +175	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

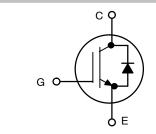
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

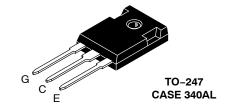


ON Semiconductor®

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20 A, 1200 V V_{CEsat} = 2.10 V E_{off} = 0.45 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB20N120IHRWG	TO-247 (Pb-Free)	30 Units / Rail

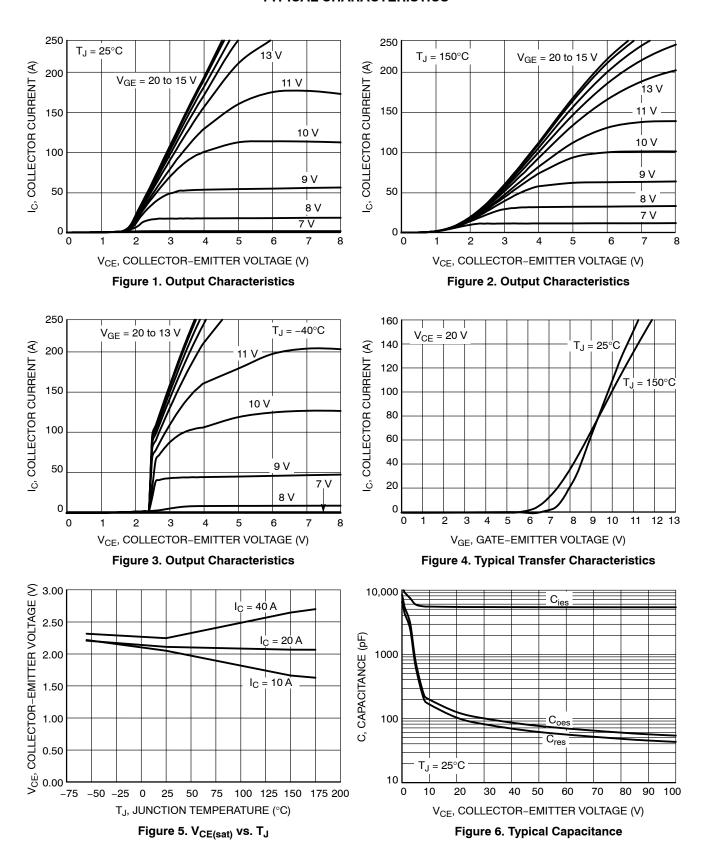
THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case	$R_{ heta JC}$	0.39	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

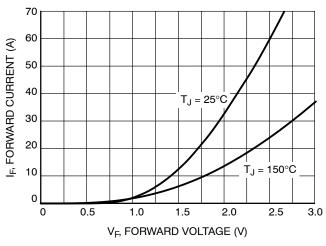
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC		•		•		
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V, I}_{C} = 500 \mu\text{A}$	V _{(BR)CES}	1200	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 20 A V _{GE} = 15 V, I _C = 20 A, T _J = 175°C	V _{CEsat}	- -	2.10 2.30	2.45 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 250 \mu A$	V _{GE(th)}	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 175°C	I _{CES}	- -	_ _	0.2 2.8	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	_	100	nA
DYNAMIC CHARACTERISTIC				•		
Input capacitance		C _{ies}	-	5320	_	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	124	_	
Reverse transfer capacitance		C _{res}	_	100	-	
Gate charge total		Q_g	_	225	-	nC
Gate to emitter charge	V _{CE} = 600 V, I _C = 20 A, V _{GE} = 15 V	Q _{ge}	_	36	-	
Gate to collector charge		Q _{gc}	-	98	-	
SWITCHING CHARACTERISTIC, INDUCT	IVE LOAD	<u>-</u>		-	<u>-</u>	
Turn-off delay time	T _J = 25°C	t _{d(off)}	-	235	-	ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 20 \text{ A}$ $R_{g} = 10 \Omega$	t _f	-	155	-	
Turn-off switching loss	V _{GE} = 0 V/ 15V	E _{off}	-	0.45	-	mJ
Turn-off delay time	T _J = 150°C	t _{d(off)}	-	255	_	ns
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 20 \text{ A}$ $R_{\alpha} = 10 \Omega$	t _f	-	250	-	
Turn-off switching loss	V _{GE} = 0 V/ 15V	E _{off}	-	1.10	-	mJ
DIODE CHARACTERISTIC						
Forward voltage	V _{GE} = 0 V, I _F = 20 A V _{GE} = 0 V, I _F = 20 A, T _J = 175°C	V _F	_ _	1.75 2.50	2.10	V

TYPICAL CHARACTERISTICS



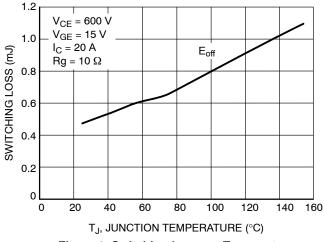
TYPICAL CHARACTERISTICS



16 V_{GE}, GATE-EMITTER VOLTAGE (V) 14 12 10 8 6 V_{CE} = 600 V 2 V_{GE} = 15 V $I_{C} = 20 A$ 0 0 50 100 150 200 250 Q_G, GATE CHARGE (nC)

Figure 7. Diode Forward Characteristics

Figure 8. Typical Gate Charge



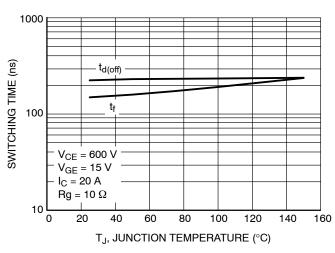
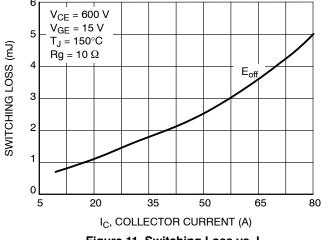


Figure 9. Switching Loss vs. Temperature

Figure 10. Switching Time vs. Temperature



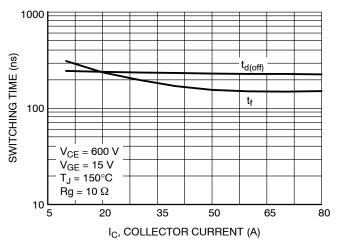


Figure 11. Switching Loss vs. I_C

Figure 12. Switching Time vs. I_C

TYPICAL CHARACTERISTICS

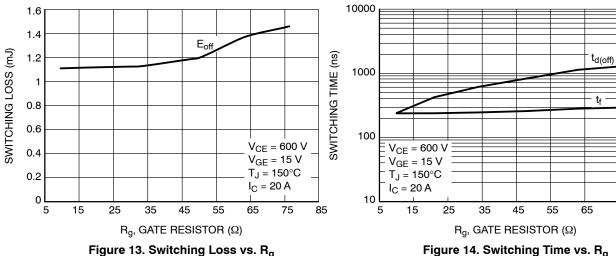


Figure 13. Switching Loss vs. R_a

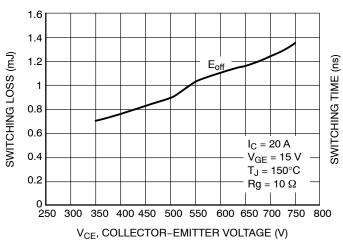
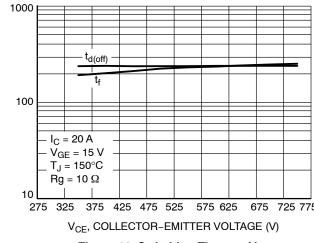


Figure 15. Switching Loss vs. V_{CE}



75

85

Figure 16. Switching Time vs. V_{CE}

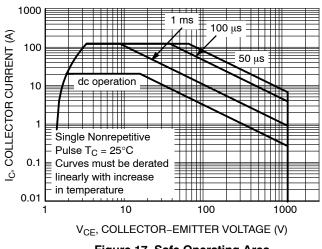


Figure 17. Safe Operating Area

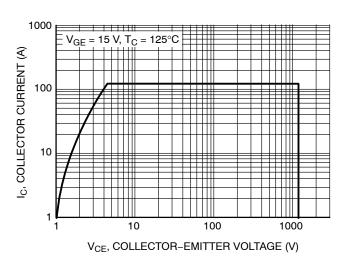


Figure 18. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS

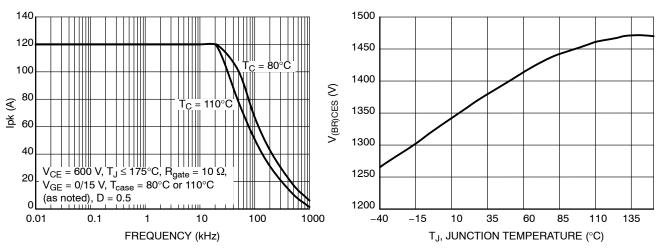


Figure 19. Collector Current vs. Switching Frequency

Figure 20. Typical $V_{(BR)CES}$ vs. Temperature

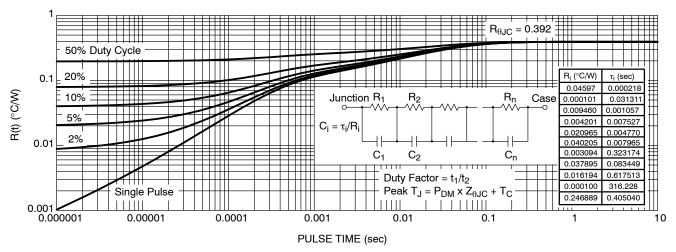


Figure 21. IGBT Transient Thermal Impedance

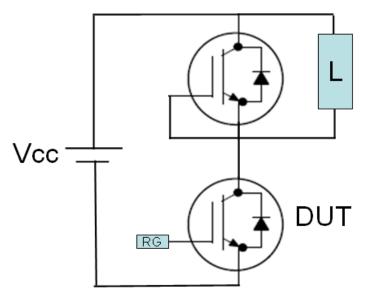


Figure 22. Test Circuit for Switching Characteristics

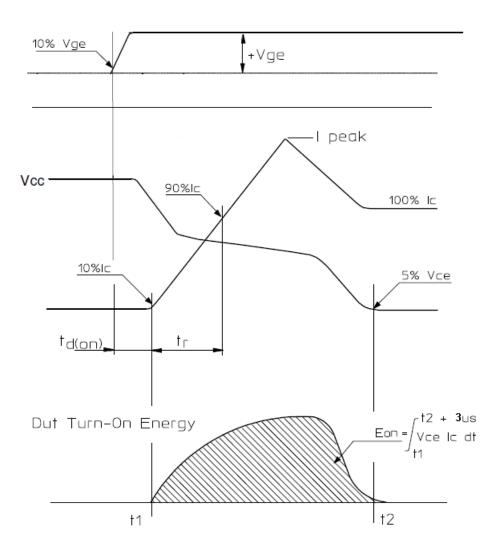


Figure 23. Definition of Turn On Waveform

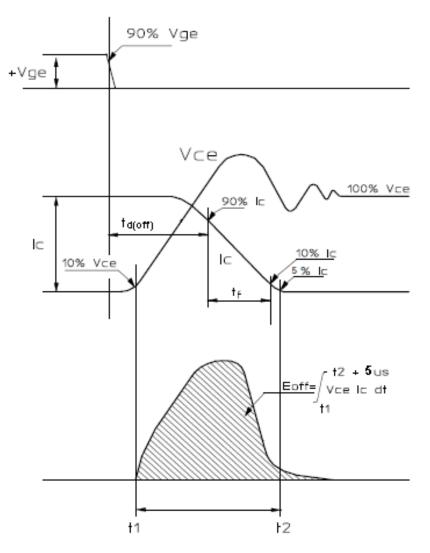
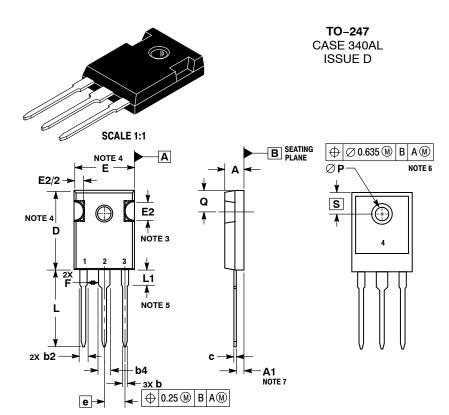


Figure 24. Definition of Turn Off Waveform



DATE 17 MAR 2017

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: MILLIMETERS.

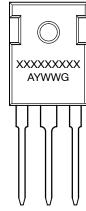
 3. SLOT REQUIRED, NOTCH MAY BE ROUNDED.

 - DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH.
 MOLD FLASH SHALL NOT EXCEED 0.13 PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREME OF THE PLASTIC BODY
- LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY
- ©P SHALL HAVE A MAXIMUM DRAFT ANGLE OF 1.5° TO THE TOP OF THE PART WITH A MAXIMUM DIAMETER OF 3.91.

 DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.70	5.30	
A1	2.20	2.60	
b	1.07	1.33	
b2	1.65	2.35	
b4	2.60	3.40	
С	0.45	0.68	
D	20.80	21.34	
E	15.50	16.25	
E2	4.32	5.49	
е	5.45 BSC		
F	2.655		
L	19.80 20.		
L1	3.81	4.32	
P	3.55	3.65	
Q	5.40 6.2		
S	6.15 BSC		

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code Α = Assembly Location

Υ = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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